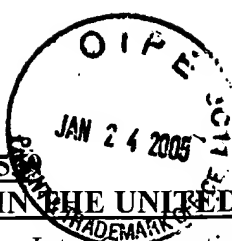


S/N 09/854,539



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Intel Corporation et al.	Examiner:	Ginette Peralta
Serial No.:	09/854,539	Group Art Unit:	2814
Filed:	May 14, 2001	Docket No.:	884.415US1
Title:	POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR USE IN MICROELECTRONIC CIRCUIT PACKAGING		
Assignee:	Intel Corporation	Customer No:	21186

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RESPONSE UNDER 37 CFR § 1.111

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

This responds to the Office Action mailed on October 20, 2004. Please amend the above-identified patent application as follows.